

Title (en)

ELECTROLYTE AND METHOD FOR ELECTROLYTIC DEPOSITION OF GOLD-COPPER ALLOYS

Title (de)

ELEKTROLYT UND VERFAHREN ZUR ELEKTROLYTISCHEN ABLAGERUNG VON GOLD-KUPFER-LEGIERUNGEN

Title (fr)

ÉLECTROLYTE ET PROCÉDÉ POUR LE DÉPÔT ÉLECTROLYTIQUE D'ALLIAGES OR-CUIVRE

Publication

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Application

EP 16197251 A 20070419

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Abstract (en)

This invention relates to an electrolyte as well as a method for the deposition of a gold-copper alloy on a substrate surface. With the electrolyte and method disclosed, deposition of gold-copper alloys with a value of carat in the range of 12 to 19 kt is possible. Beneath a source of gold and copper, the inventive electrolyte comprises potassium cyanate (KCN) in a concentration capable to maintain a copper to KCN ratio in the range of 3 to 7, and at least one complexing agent of the group consisting of ethylenediamine tetraacetic acid, diethylenetriamine pentaacetic acid, nitrilo-triacetic acid, ethylenediamine tetraacetic acid [EDTA], diethylenetriamine pentaacetic acid and nitrilotriacetic acid [NTA] Hydroxyethyl imino diacetic acid [HEIDA], nitrilo propionic diacetic acid [NPDA], imino diacetic acid [IDA], nitrilo trimethylphosphoric acid [NTMA, Dequest 2000], triethanol amine [TEA].

IPC 8 full level

C25D 3/58 (2006.01); **C25D 3/62** (2006.01)

CPC (source: EP)

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Citation (search report)

- [XY] EP 0193848 A1 19860910 - EMMENEGGER HEINZ
- [XY] GB 1375611 A 19741127
- [XY] GB 2053276 A 19810204 - ALIPRANDINI P

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